PCB MANUFACTURING SPECIFICATIONS "LTK-MW TX/RX 2019 Q2"

SPECIFICATIONS

NOTE#	NOTE
1	ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK
2	SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION
3	ALL MATERIALS SHALL BE ROHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN ROHS ASSEMBLY. ROHS LOGO SHALL BE MARKED IN SILKSCREEN INK NEAR BY THE SUPPLIER.
4	COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS
5	ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-CONDUCTIVE, PERMANENT INK.
6	MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM_NOTES" BY THE TEXT "YOU CAN PLACE MARKINGS HERE".
7	MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS OTHERWISE NOTED ONTO THE LAYER "PCBM_NOTES"
8	SUPPLIER SHALL CHECK PCBM_NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS
9	MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES

Layer Stack Legend



SPECIFICATIONS

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LENGHT	122		
WIDTH	96.5		
LAYERS	2		
MATERIAL	FR-4		
MATERIAL MIN TG	130-140		
TRACK WIDTH/CLEARANCE	8 mils / 8 mils		
THICKNESS	1.6mm		
COPPER THICKNESS	35um (1oz)		
SOLDERMASK	YES, TOP AND BOTTOM		
SOLDERMASK COLOR	RED		
SILKSCREEN	YES, TOP AND BOTTOM		
SILKSCREEN COLOR	WHITE		
SURFACE FINISH	HASL LEAD FREE		
GOLD FINGERS	NO		
CHAMFERING	NO		
IMPEDANCE CONTROL	NO		
HALF-CUT/CASTELLATED HOLES	NO		
BURIED/BLIND VIAS	NO		
VIAS FILLED WITH RESIN	NO		
CARBON MASK	NO		
COUNTERSINKS/COUNTERBORES	NO		
Z-AXIS MILLING	NO		
PEELABLE SOLDERMASK	NO		

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Total thickness: 1.66mm

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NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE

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